





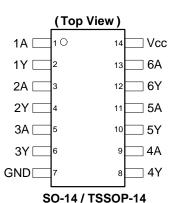
Description

The 74LVC04A provides six independent inverter buffers. The device is designed for operation with a power supply range of 1.65V to 5.5V. The inputs are tolerant to 5.5V allowing this device to be used in a mixed voltage environment. The device is fully specified for partial power down applications using IOFF. The IOFF circuitry disables the output preventing damaging current backflow when the device is powered down.

The gates perform the positive Boolean function:

$$Y = \overline{A}$$

Pin Assignments



Features

- Wide Supply Voltage Range from 1.65V to 5.5V
- Sinks or Sources 24mA at V_{CC} = 3.3V
- CMOS Low Power Consumption
- IOFF Supports Partial-Power-Down Mode Operation
- Inputs or Outputs Accept up to 5.5V
- Inputs can be Driven by 3.3 V or 5.5V Allowing for Voltage Translation Applications
- ESD Protection Exceeds JESD 22
 - 200-V Machine Model (A115-A)
 - 2000-V Human Body Model (A114-A)
 - Exceeds 1000-V Charged Device Model (C101C)
- Latch-Up Exceeds 250mA per JESD 78, Class II
- Range of Package Options SO-14 and TSSOP-14
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)

Applications

- Voltage Level Shifting
- General Purpose Logic
- Power Down Signal Isolation
- Wide Array of Products such as:
 - PCs, Networking, Notebooks, Ultrabooks, Netbooks
 - Computer Peripherals, Hard Drives, CD/DVD ROM
 - TV, DVD, DVR, Set-Top Box

Notes:

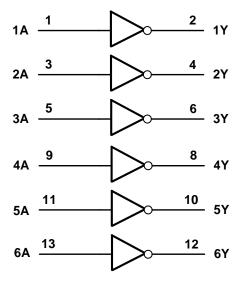
- 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant.
- 2. See https://www.diodes.com/quality/lead-free/ for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.



Pin Descriptions

Pin Number	Pin Name	Description	
1	1A	Data Input	
2	1Y	Data Output	
3	2A	Data Input	
4	2Y	Data Output	
5	3A	Data Input	
6	3Y	Data Output	
7	GND	Ground	
8	4Y	Data Output	
9	4A	Data Input	
10	5Y	Data Output	
11	5A	Data Input	
12	6Y	Data Output	
13	6A	Data Input	
14	Vcc	Supply Voltage	

Logic Diagram



Function Table

Inputs	Outputs
Α	Υ
Н	L
L	Н



Absolute Maximum Ratings (Note 4) (@T_A = +25°C, unless otherwise specified.)

Symbol	Description		Rating	Unit
ESD HBM	Human Body Model ESD Protection		2	KV
ESD CDM	Charged Device Model ESD Protection		1	KV
ESD MM	Machine Model ESD Protection		200	V
V _{CC}	Supply Voltage Range		-0.5 to 6.5	V
VI	Input Voltage Range		-0.5 to 6.5	V
Vo	Voltage Applied to Output in High Impedance or IOFF St	Voltage Applied to Output in High Impedance or I _{OFF} State		
Vo	Voltage Applied to Output in High or Low State		-0.3 to V _{CC} +0.5	V
I _{IK}	Input Clamp Current	V _I <0	-50	mA
lok	Output Clamp Current	V _O <0	-50	mA
Io	Continuous Output Current		50	mA
_	Continuous Current Through Vdd or GND		±100	mA
TJ	Operating Junction Temperature	-40 to +150	°C	
T _{STG}	Storage Temperature	-65 to +150	°C	
Ртот	Total Power Dissipation		500	mW

Note:

Recommended Operating Conditions (Note 5) (@T_A = +25°C, unless otherwise specified.)

Symbol	Parameter	Conditions	Min	Max	Unit	
V_{CC}	Supply Voltage		1.65	5.5	V	
V_{I}	Input Voltage		0	5.5	V	
	Output Voltage	Active Mode	0	V_{CC}	V	
Vo		V _{CC} = 0V; Power Down Mode	0	5.5	V	
A+/A>/	land Tanakiia Diama Fall Data	V _{CC} = 1.65V to 2.7V	_	20	0.4	
Δt/ΔV	Input Transition Rise or Fall Rate	V _{CC} = 2.7V to 5.5V	_	10	ns/V	
T_A	Operating Free-Air Temperature	_	-40	+125	°C	

Notes:

^{4.} Stresses beyond the absolute maximum may result in immediate failure or reduced reliability. These are stress values and device operation should be within recommend values.

^{5.} Unused inputs should be held at V_{CC} or Ground.



Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

Comple of	Danamatan	Toot Conditions	V	T _A = -40°C	to +85°C	T _A = -40°C	to +125°C	11:4
Symbol	Parameter	Test Conditions	V _{cc}	Min	Max	Min	Max	Unit
		_	1.65V to 1.95V	0.65 × V _{CC}	_	0.65 × V _{CC}	_	
	High-Level Input	_	2.3V to 2.7V	1.7	_	1.6	_	\ /
V _{IH}	Voltage	_	2.7V to 3.6V	2.0	_	2.0	_	V
		_	4.5V to 5.5V	0.7 × V _{CC}	_	2.0	_	
		_	1.65V to 1.95V	_	0.35 × V _{CC}	_	0.35 × V _{CC}	
.,,	Low-Level Input	_	2.3V to 2.7V	_	0.7	_	0.7	\ /
V _{IL}	Voltage	_	2.7V to 3.6V	_	0.8	_	0.8	V
		_	4.5V to 5.5V	_	0.3 × V _{CC}	_	0.3 × V _{CC}	
		I _{OH} = -100μA	1.65V to 3.6V	V _{CC} - 0.2	_	V _{CC} - 0.3	_	
		I _{OH} = -4mA	1.65V	1.2	_	_	_	
\ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \	High Level Output	I _{OH} = -8mA	2.3V	1.9	_	_	_	V
V _{OH}	Voltage	10 1	2.7V	2.2	_	2.05	_	V
		I _{OH} = -12mA	3.0V	2.3	_	2.1	_	
		I _{OH} = -24mA	3.0V	2.2	_	2.0	_	
		I _{OH} = 100μA	1.65V to 5.5V	_	0.2	_	0.3	
		I _{OH} = 4mA	1.65V	_	0.45	_	0.6	
\/	High-Level Output	I _{OH} = 8mA	2.3V	_	0.70	_	0.85	V
V _{OL}	Voltage	1 12m A	2.7V	_	0.40	_	0.6	V
		I _{OH} = 12mA	3.0V	_	0.55	_	0.6	
		I _{OH} =-24mA	3.0V	_	0.55	_	0.6	
Iı	Input Current	V _I =GND to 5.5V	3.6V	_	±5	_	±20	μA
I _{OFF}	Power Down Leakage Current	V_I or $V_O = 0V$ to 3.6V	0	_	10	_	20	μΑ
Icc	Supply Current	$V_I = GND \text{ or } V_{CC}$ $I_O = 0$	3.6V	_	10	_	40	μΑ
Δlcc	Additional Supply Current	One input at V _{CC} – 0.6V Other	2.7V to 3.6V	_	500	_	5000	μΑ



Switching Characteristics

Currente ed	Downwater	Test	V	T,	_A = +25°	C	-40°C to	o +85°C	-40°C to	+125°C	l lm!t	
Symbol	Parameter	Conditions	V _{cc}	Min	Тур	Max	Min	Max	Min	Max	Unit	
			1.65V to1.95V	0.5	4.1	7.5	0.5	8.0	0.5	9.5		
	Propagation Delay A _N to Y _N Figure	Propagation Delay	F: 4	2.3V to 2.7V	0.5	3.6	7.0	0.5	7.5	0.5	9.0	
t _{PD}		Figure 1	2.7V	0.5	3.0	5.3	0.5	5.5	0.5	7.0	ns	
			3V to 3.6V	0.5	2.5	4.3	0.5	4.5	0.5	6.0		
t _{SK(0)}	Output Skew Time	_	3V to 3.6V	I	ı	_	1	1.0		1.5	ns	

Operating Characteristics (@T_A = +25°C, unless otherwise specified.)

	Parameter		V _{CC} = 1.8V	V _{CC} = 2.5V	$V_{CC} = 3.3V$	V _{CC} = 5V	Unit
			Тур	Тур	Тур	Тур	Ollit
C _{pd}	Power Dissipation Capacitance per Gate	f = 10 MHz	7.0	7.5	8.0	8.6	pF
Cı	Input Capacitance	$V_i = V_{CC} - or$ GND	4	4	4	4	pF

Package Characteristics

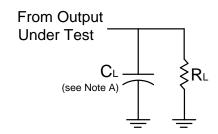
Symbol	Parameter	Test Conditions	V _{cc}	Min	Тур	Max	Unit
0	Thermal Resistance	SO-14	(Note 6)		TBD	1	°C/W
ӨЈА	Junction-to-Ambient	TSSOP-14	(Note 6)		159	_	C/VV
	Thermal Resistance	SO-14	(Note 6)		TBD	_	°C/W
θ _{JC}	Junction-to-Case	TSSOP-14	(Note 6)	_	25		C/VV

Note: 6. Test condition for SO-14 and TSSOP-14: Device mounted on FR-4 substrate PC board, 2oz copper, with minimum recommended pad layout.

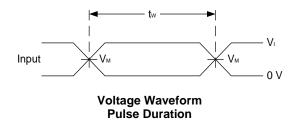
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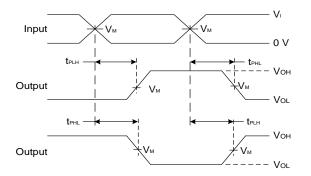


Parameter Measurement Information



V	Inputs		V		В	
V _{CC}	Vı	t _r /t _f	V_{M}	C _L	R∟	
1.8V ±0.15V	Vcc	≤2ns	V _{CC} /2	30pF	1ΚΩ	
2.5V ±0.2V	Vcc	≤2ns	V _{CC} /2	30pF	500Ω	
3.3V ±0.3V	3V	≤2.5ns	1.5V	50pF	500Ω	
5V ±0.5V	V _{CC}	≤2.5ns	V _{CC} /2	50pF	500Ω	





Voltage Waveform Propagation Delay Times Inverting and Non Inverting Outputs

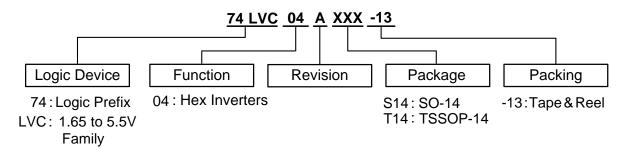
Notes: A. Includes test lead and test apparatus capacitance.

- B. All pulses are supplied at pulse repetition rate ≤ 10 MHz.
 C. Inputs are measured separately one transition per measurement.
- D. t_{PLH} and t_{PHL} are the same as t_{PD} .

Figure 1. Load Circuit and Voltage Waveforms



Ordering Information

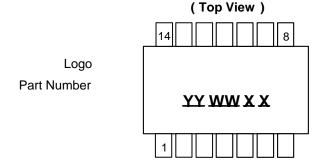


	Device	Package	Packaging	13" Tape and Reel	
_		Code	(Note 7)	Quantity	Part Number Suffix
Pby Lead free Green	74LVC04AS14-13	S14	SO-14	2500/Tape & Reel	-13
Pb.	74LVC04AT14-13	T14	TSSOP-14	2500/Tape & Reel	-13

Notes: 7. The taping orientation and tape details can be found at http://www.diodes.com/datasheets/ap02007.pdf

Marking Information

(1) SO-14, TSSOP-14



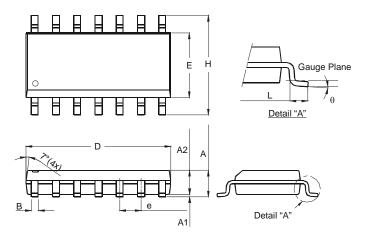
Part Number	Package
74LVC04AS14	SO-14
74LVC04AT14	TSSOP-14



Package Outline Dimensions (All dimensions in mm.)

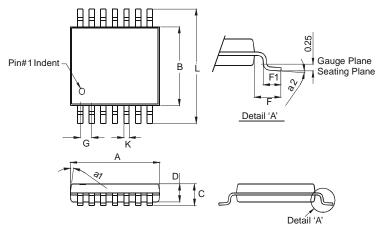
Please see http://www.diodes.com/package-outlines.html for the latest version.

SO-14



	SO-14	
Dim	Min	Max
Α	1.47	1.73
A 1	0.10	0.25
A2	1.45	Тур
В	0.33	0.51
D	8.53	8.74
Е	3.80	3.99
е	1.27	Тур
Н	5.80	6.20
L	0.38	1.27
θ	0°	8°
All Di	mensions	s in mm

TSSOP-14

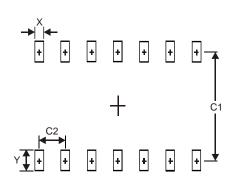


TSSOP-14				
Dim	Min	Max		
a1	7° (4X)			
a2	0°	8°		
Α	4.9	5.10		
В	4.30	4.50		
C	-	1.2		
D	0.8	1.05		
F	1.00 Typ			
F1	0.45	0.75		
G	0.65 Typ			
K	0.19	0.30		
L	6.40 Typ			
All Dimensions in mm				



Suggested Pad Layout

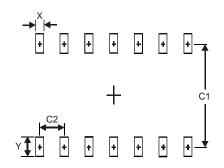
Please see http://www.diodes.com/package-outlines.html for the latest version.



Dimensions	Value (in mm)	
Х	0.60	
Y	1.50	
C1	5.4	
C2	1.27	

TSSOP-14

SO-14



Dimensions	Value (in mm)
Х	0.45
Y	1.45
C1	5.9
C2	0.65



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